

MECHANICAL CASE OUTLINE

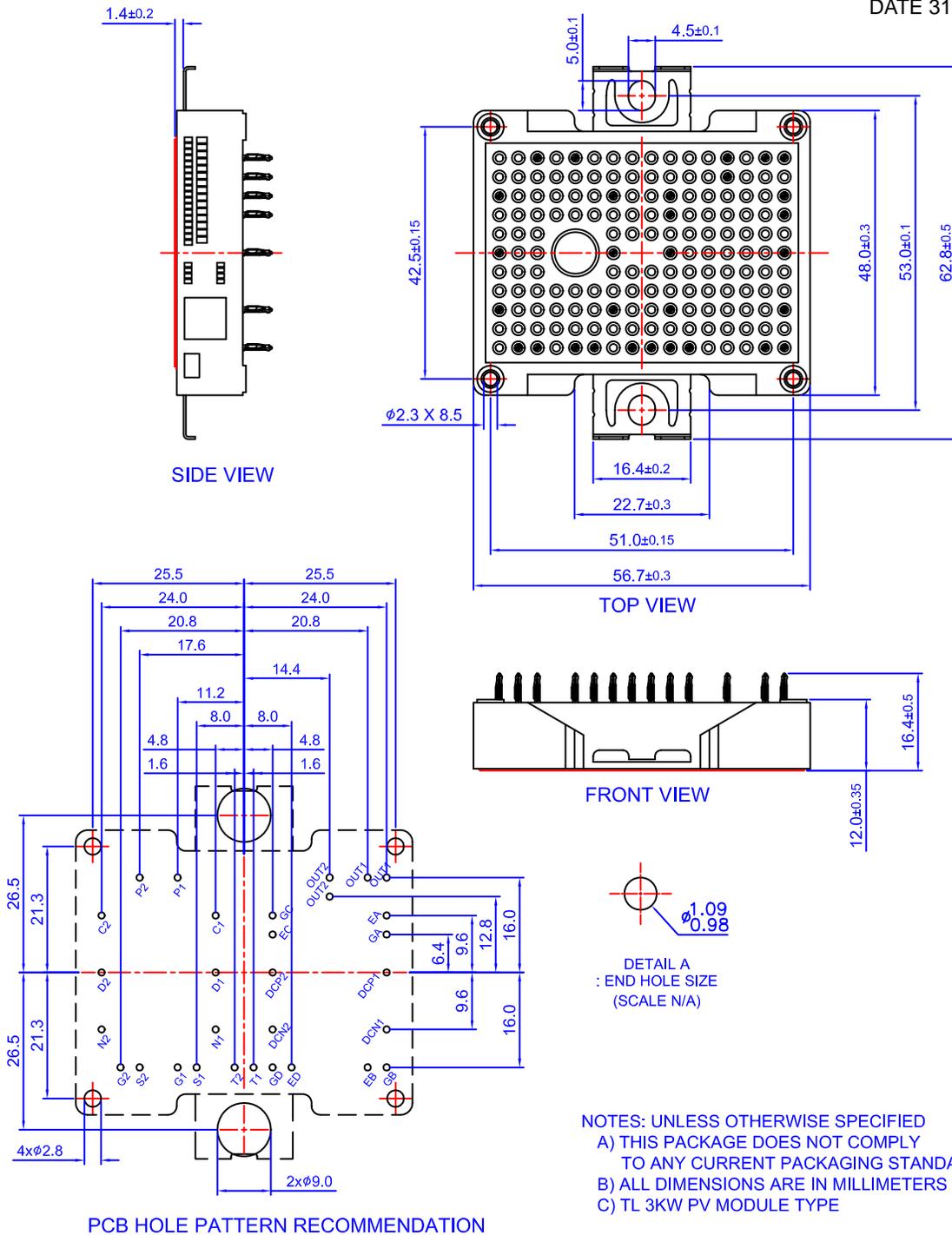
PACKAGE DIMENSIONS

ON Semiconductor®



HF2EA-P30 / 30LD, HPM, F2 PKG, PRESSFIT TERMINAL, TL 3KW PV MODULE CASE MODCU ISSUE O

DATE 31 DEC 2016



DETAIL A
: END HOLE SIZE
(SCALE N/A)

- NOTES:** UNLESS OTHERWISE SPECIFIED
- A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD
 - B) ALL DIMENSIONS ARE IN MILLIMETERS
 - C) TL 3KW PV MODULE TYPE

- PIN-GRID 3.2mm
- TOLERANCE OF PCB HOLE PATTERN $\pm \varnothing 0.1$

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	HF2EA-P30 / 30LD, HPM, F2 PKG, PRESSFIT TERMINAL	PAGE 1 OF 2

